

MEG00-001
Serial number 09/684,519



TO: COMMISSIONER OF PATENTS AND TRADEMARKS
Washington, D.C. 20231

From : George O. Saile (Reg. No. 19,572)
28 Davis Avenue
Poughkeepsie, NY 12603

Date: December 15, 2002

REF: APPLICANT : Jin-Yuan Lee
SERIAL NO. : 09/684,519
ART UNIT : 2841
FILING DATE : 10/10/00
ATT'Y NO. : MEG01-001
EXAMINER : Bui, Hung S.
TITLE : A THERMALLY COMPLIANT PCB
SUBSTRATE FOR THE APPLICATION
OF CHIP SCALE PACKAGES.

RECEIVED
JAN 15 2003
TECHNOLOGY CENTER 2800

10

~17-03
JAN

AMENDMENT AND RESPONSE TO OFFICE ACTION

Sir:

In response to an office action mailed on 11/04/02
please consider the following amendments and remarks with
respect to the above referenced application.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal service as First
Class mail in an envelop addressed to the Commissioner of
Patents and Trademarks, Washington, D.C. 20231, on

January 6, 2003

Stephen B. Ackerman (Reg. No 37,761)


Signature

1/6/03
Date